



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Akira Matsuda et al.**

Group Art Unit: **1794**

Serial Number: **10/719,020**

Examiner: **Michael E. Lavilla**

Filed: **November 24, 2003**

P.T.O. Confirmation No.: **9168**

For: **METHOD FOR PREPARING A CIRCUIT BOARD MATERIAL HAVING A
CONDUCTIVE BASE AND A RESISTANCE LAYER**

Attorney Docket No.: **032130**

Customer Number: **38834**

DECLARATION UNDER 37 CFR §1.132

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I, Akira Matsuda, hereby declare and state that:

(1) I am familiar with the contents of the United States Patent Application Serial No. 10/719,020, filed on November 24, 2003, claiming the priority of Japanese Patent Application No. 2002-341813 filed on November 26, 2002.

(2) I am one of the inventors of the invention of United States Patent Application Serial No. 10/719,020.

(3) I prepared a declaration under 37CFR§ 1.132 ("1st Declaration") on March 5, 2006, which

Application No. 10/719,020
Declaration under 37CFR1.132

was filed in the United States Patent And Trademark Office on March 10, 2006.

(4) In § 12 of the Office Action mailed on February 6, 2008, the Examiner raised a question whether the flow conditions were same between the examples in the specification and the examples in the 1st Declaration.

(5) Comparative Examples 3 and 4 were prepared and evaluated in the same manner as described in the specification at pages 13 to 20, as declared at page 2 of the 1st Declaration. Thus, the flow conditions in plating were the same in all of Examples 1-5 and Comparative Examples 1-4.

(6) I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like are punishable by fine or imprisonment, or both, under the laws of the United State and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Akira Matsuda

Akira Matsuda

2008.7.6.

Date